

**RS1001FL~RS1008FL**

**SMALL SURFACE MOUNT FAST DIODES**

**VOLTAGE** 100 to 800 Volts **CURRENT** 1.0 Amperes

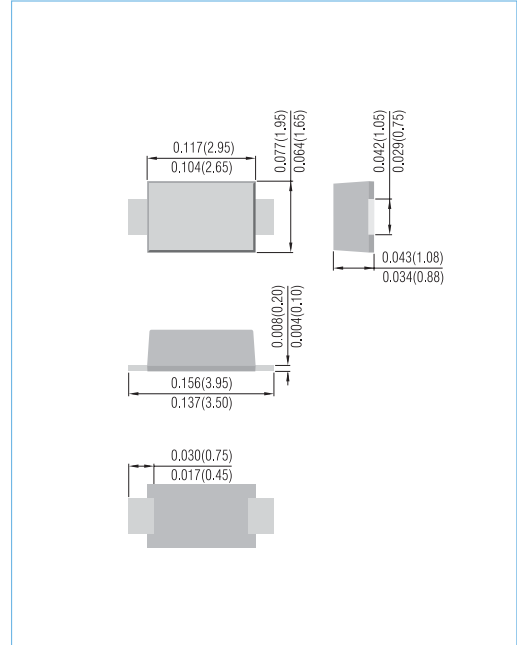
**SOD-123FL/DO-219AB** Unit: inch ( mm )

**FEATURES**

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- Glass Passivated Chip Junction
- High temperature soldering : 260°C / 10 seconds at terminals
- Pb free product : 99% Sn above can meet RoHS environment substance directive request

**MECHANICAL DATA**

- Case: JEDEC DO-219AB, Molded plastic over passivated junction
- Terminals: Solderable per MIL-STD-750, Method 2026
- Standard Packaging : 8mm tape (EIA-481)
- Approx. Weight: 0.0168 gram



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Rating	Test condition	Symbol	RS1001FL	RS1002FL	RS1004FL	RS1006FL	RS1008FL	Units
Maximum repetitive peak reverse voltage		$V_{RRM}$	100	200	400	600	800	V
Maximum RMS voltage		$V_{RMS}$	70	140	280	420	560	V
Maximum DC blocking voltage		$V_{DC}$	100	200	400	600	800	V
Maximum average forward rectified current	$T_D=65^{\circ}C$ $T_A=45^{\circ}C$	$I_{F(AV)}$	1.4 0.5					A
Maximum instantaneous forward voltage	0.7A	$V_F$	1.15					V
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^{\circ}C$ $T_A=125^{\circ}C$	$I_R$	10 50					$\mu A$
Thermal resistance junction to ambient air		$R_{\theta JA}$	180					K/W
Operating junction and storage temperature range		$T_J, T_{STG}$	-50 TO + 150					$^{\circ}C$
Reverse recovery time	$I_F=0.5A$ $I_R=1A$ $t_r=0.25A$	$t_{rr}$	150		250		500	nS
Typical capacitance	4V,1MHz	$C_J$	9					pF